

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph beginning at page 36, line 2, with the following rewritten paragraph:

-- ~~The A~~ film carrier tape for mounting electronic components ~~according to the present invention includes~~ comprises an insulating film and, on the surface thereof, an inner connection terminal, an outer connection terminal and a wiring for connecting these terminals, and further ~~comprises~~ includes a solder resist layer covered in such a way that the connection terminals are exposed, and the tape secures ~~electric~~ an electrical connection of a connection terminal of an electronic component and the inner connection terminal by applying an ultrasonic wave on the inner connection terminal in mounting the electronic component;

~~wherein~~. The wiring positioned from a part where the inner connection terminal is electrically connected with the connection terminal of the electronic component to the edge of the solder resist layer and wiring in a 1000  $\mu$ m length from the edge of the solder resist, which wiring is protected by the solder resist layer, are formed in an almost straight shape.

~~\_\_\_\_\_~~ The film carrier tape for mounting electronic components having ~~such a the above structure according to the present invention does not receive any~~ concentration of stress ~~in application with when~~ an ultrasonic wave is applied and thereby cracks or ~~disconnection are hardly caused~~ disconnections in the wiring pattern are virtually eliminated. --